

# YETDA INDUSTRY LTD.

## Technical Data Sheet

MODEL NO : S280ANG4

Features :

- 1.0x0.5mm SMT LED, 0.6mm thickness
- Compatible with automatic placement equipment
- Compatible with reflow solder process

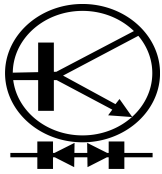
Applications :

- Indicators
- Automotive : backlighting in dashboard and switch
- Backlight for LCD

Dice material	Emitted color	Lens Color
InGaN/GaN	Pure Green	Water Clear

Electrical /Optical Characteristics(Ta=25°C)

Parameter	Test Condition	Symbol	Value			Unit
			Min	Typ	Max	
Dominant Wavelength	IF=20mA	$\lambda_d$	515	520		nm
Forward voltage	IF=20mA	VF	2.8		3.4	V
Luminous intensity	IF=20mA	Iv	200	300	500	mcd
Viewing angle at 50% Iv	IF=10mA	$2\theta_{1/2}$		120		Deg
Reverse current	VR=5V	IR			10	$\mu$ A

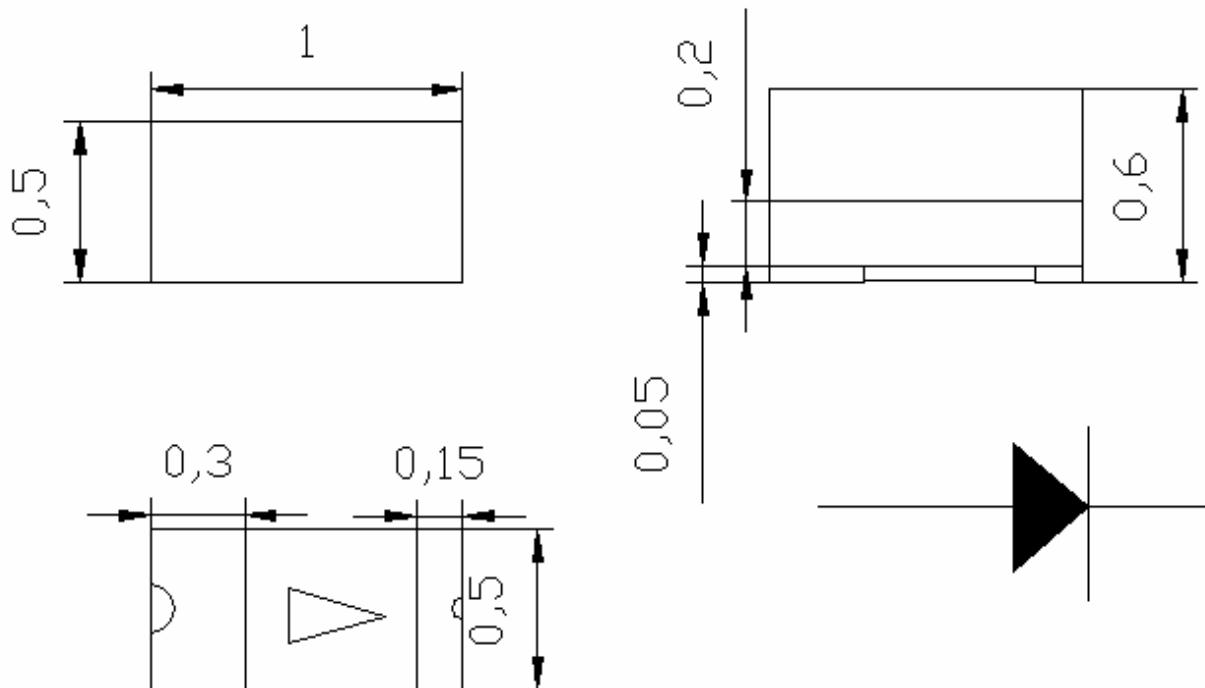


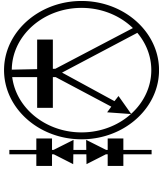
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Absolute Maximum Ratings(Ta=25°C)

Parameter	Symbol	Value	Unit
Power dissipation	Pd	108	mW
Forward current	I <sub>F</sub>	30	mA
Reverse voltage	V <sub>R</sub>	5	V
Operating temperature range	Top	-40 ~+80	°C
Storage temperature range	Tstg	-40 ~+85	°C
Peak pulsing current (1/8 duty f=1kHz)	I <sub>FP</sub>	125	mA

## PACKAGING DIMENSIONS (mm):

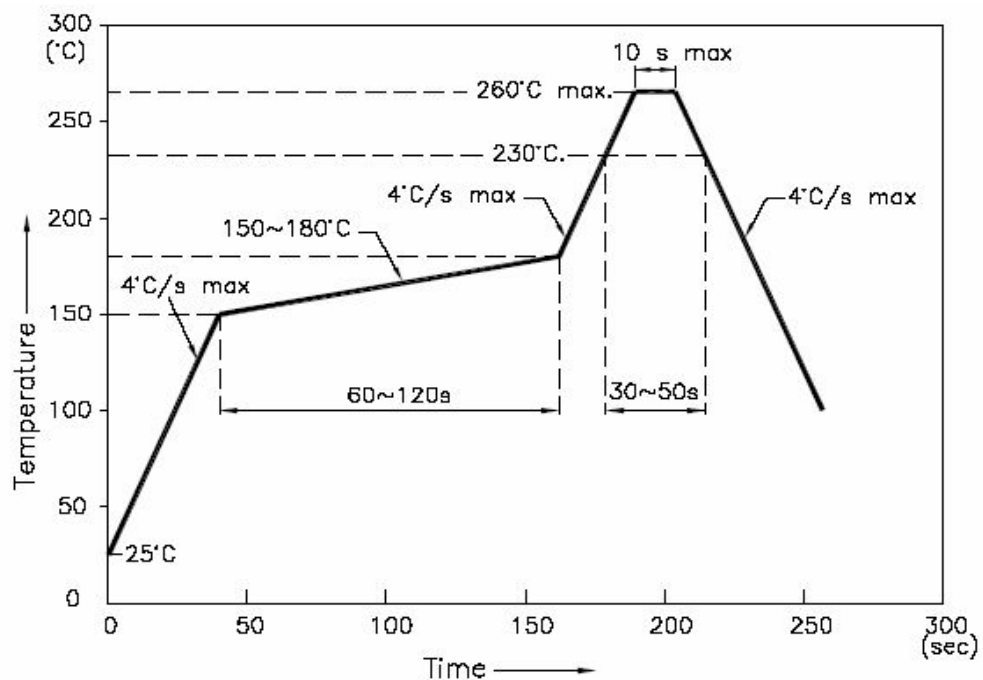




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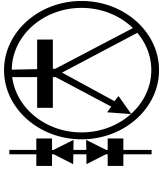
<b>Precautions For Use :</b>
<b>Over– current– proof</b>
Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change ( Burn out will happen )
<b>Storage</b>
1. The operation of temperature and R.H. are : $5^{\circ}\text{C} \sim 30^{\circ}\text{C}$ , 60%R.H. Max.
2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a dampproof box with desiccating reagent. Considering the tape life, we suggest our customers to use our products within 1.5 year ( from production date ) .
3. It's recommended to bake before soldering when the package is unsealed after 72 hrs. The condition is : $60^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 15hrs.

## ■ Reflow Temp/Time



### NOTES:

1. We recommend the reflow temperature  $245^{\circ}\text{C} (\pm 5^{\circ}\text{C})$ . the maximum soldering temperature should be limited to  $260^{\circ}\text{C}$ .
2. dont cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.



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## ■ Soldering iron

Basic spec is  $\leq 5\text{sec}$  when  $260^{\circ}\text{C}$ . If temperature is higher, time should be shorter ( $+10^{\circ}\text{C} \rightarrow -1\text{sec}$ ). Power dissipation of iron should be smaller than 20W, and temperatures should be controllable. Surface temperature of the device should be under  $230^{\circ}\text{C}$ .

- **Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow 、 solder etc.**